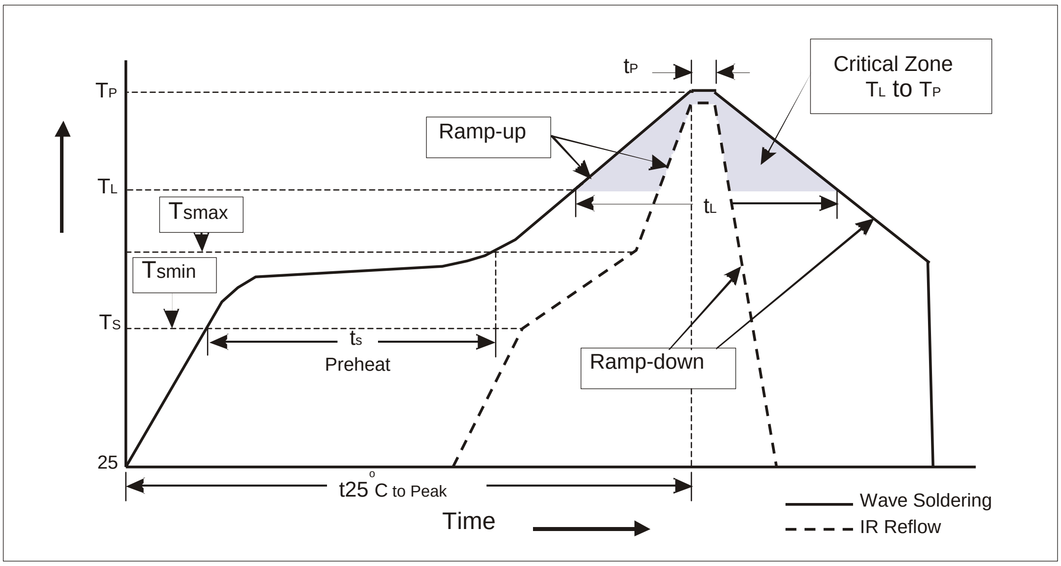
SMBJ Series (TVS Diode) Reflow Profile

Suggested thermal profiles for soldering processes

1.Storage environment: Temperature=10 °C~35 °C Humidity=65%±15%
2.Reflow soldering of surface-mount devices



3.Flow (wave)soldering (solder dipping)

Profile Feature	Soldering Condition
Average ramp-up rate(T_L to T_P)	<3 ℃/sec
Preheat	
-Temperature Min(Tsmin)	100 ℃
-Temperature Max(Tsmax)	150 ℃
-Time(min to max)(ts)	60~120sec
Tsmax to T_L	
-Ramp-upRate	<3 ℃/sec
Time maintained above:	
-Temperature(T_L)	183 ℃
-Time(t_L)	60~150sec
Peak Temperature(T_P)	255 ℃-0/+5 ℃
Time within 5 °C of actual Peak Temperature(t_P)	10~30sec
Ramp-down Rate	<6 ℃/sec
Time 25℃ to Peak Temperature	<6 minutes